（3583）

Q3 Results

Oct 2014

Business Overview

Products

Future Prospect

Income Statement

	2013	2013/3Q	2014/3Q	2013/1-3Q	2014/1-3Q
Revenues	3,067,640	775,875	680,904	2,156,560	1,878,498
Gross Profit	982,937	268,409	282,968	681,732	647,694
Gross Margin	32.00%	34.59%	41.56%	31.61%	34.48%
Operating Expenses	629,202	146,684	183,200	454,171	499,708
Operating Income	353,735	121,725	99,768	227,561	147,986
Operating Margin	11.50%	15.69%	14.65%	10.55%	7.88%
Income Before Tax	327,800	100,749	94,395	212,934	151,465
Income Before Tax margin	10.70%	12.99%	13.86%	9.87%	8.06%
Net Income	249,417	78,057	77,859	162,441	115,757
EPS	3.13	0.96	0.96	2.05	1.43

Business Overview

Revenues and Gross Margin

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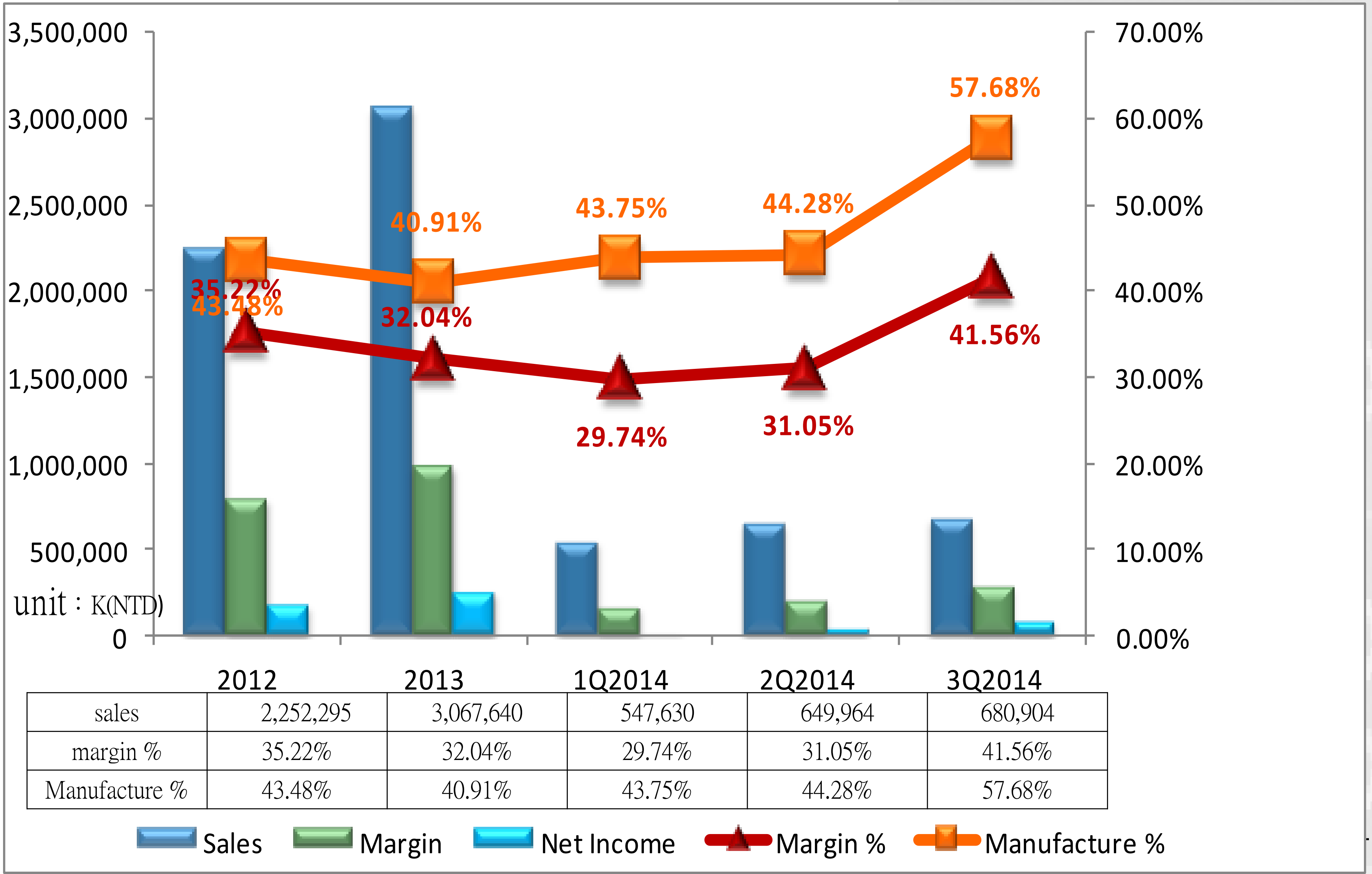
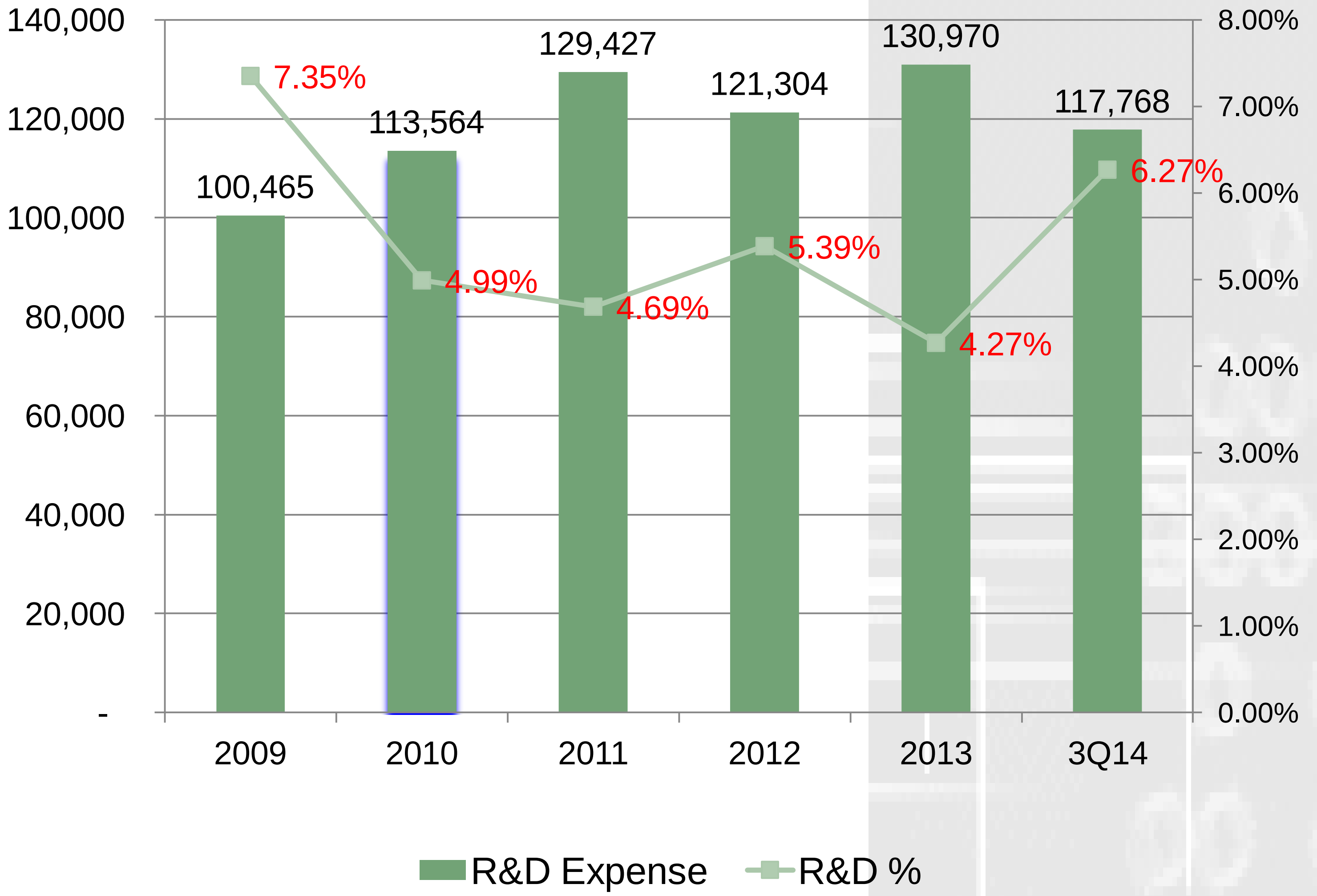


unit：K(NTD)

	2012	2013	1Q2014	2Q2014	3Q2014
sales	2,252,295	3,067,640	547,630	649,964	680,904
margin %	35.22%	32.04%	29.74%	31.05%	41.56%
Manufacture %	43.48%	40.91%	43.75%	44.28%	57.68%

R & D Expense


140,000
120,000
100,000
80,000
60,000
40,000
20,000
-
8.00%
7.00%
6.00%
5.00%
4.00%
3.00%
2.00%
1.00%
0.00%
100,465
113,564
129,427
121,304
130,970
117,768
7.35%
4.99%
4.69%
5.39%
4.27%
6.27%
2009
2010
2011
2012
2013
3Q14
R&D Expense
R&D %

Products

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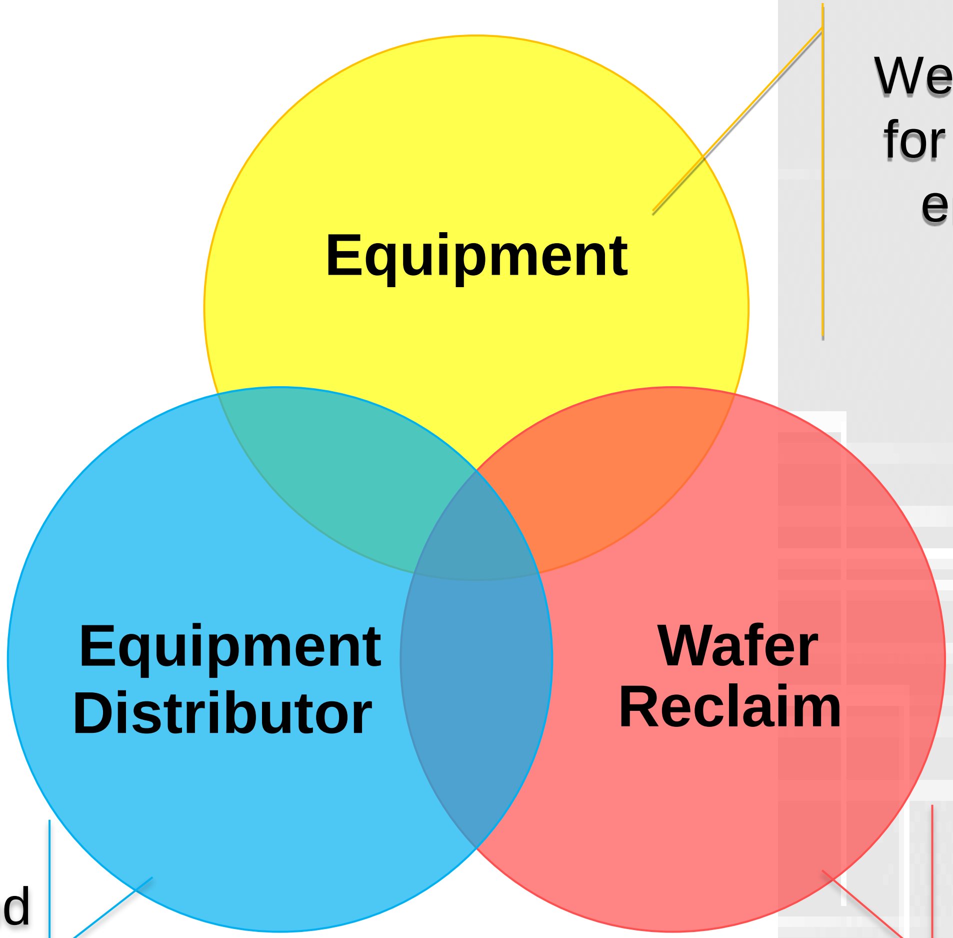


Wet process equipment for front-end and back-end semiconductor/ Optoelectronics

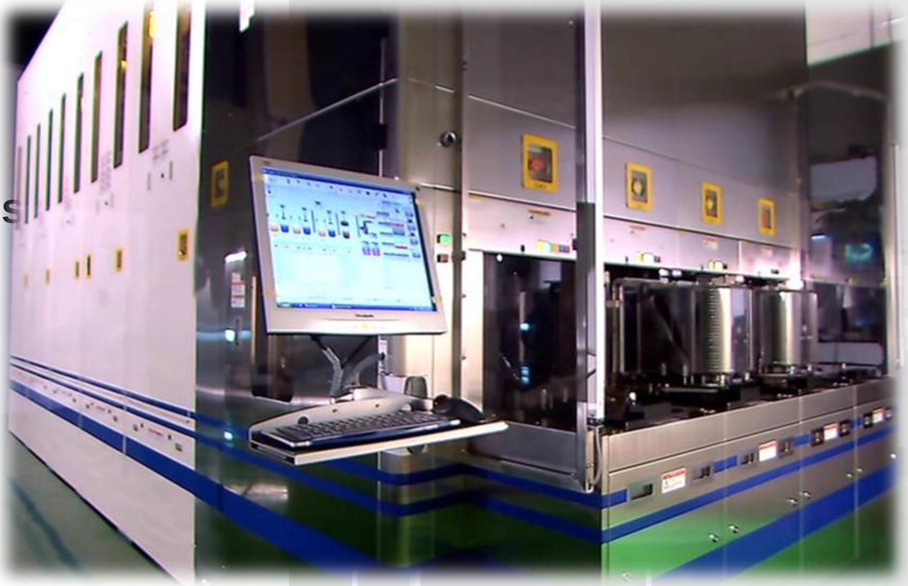
Semiconductor and optoelectronics process equipment

12” Wafer Reclaim

Equipment

Wet process equipment

- Single wafer/ Batch type
  - 8”/12’ Advanced packaging
    - InFo/RDL/bumping / TSV / 2.5D
  - 6”/ 8”/12” Front-end special process
    - FP、RF 、CMOS 、LCD/TP controller、Power IC
    - MEMS/ III-V for PA 、RF IC
  - HB LED fully-automatic process



Products

Equipment

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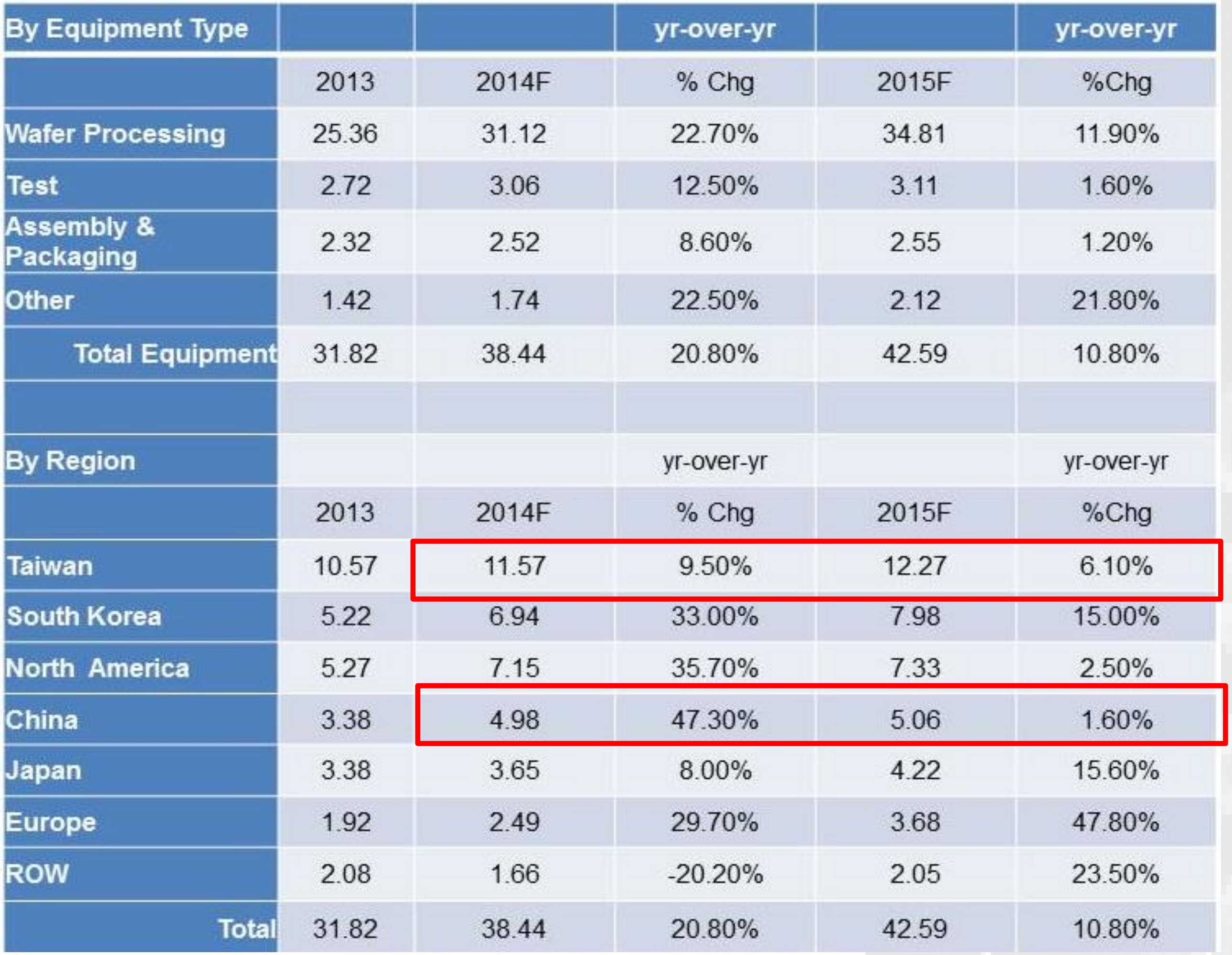
2014 Mid-Year Equipment Forecast by Market Region



By Equipment Type			yr-over-yr		yr-over-yr
	2013	2014F	% Chg	2015F	%Chg
Wafer Processing	25.36	31.12	22.70%	34.81	11.90%
Test	2.72	3.06	12.50%	3.11	1.60%
Assembly & Packaging	2.32	2.52	8.60%	2.55	1.20%
Other	1.42	1.74	22.50%	2.12	21.80%
Total Equipment	31.82	38.44	20.80%	42.59	10.80%
By Region			yr-over-yr		yr-over-yr
	2013	2014F	% Chg	2015F	%Chg
Taiwan	10.57	11.57	9.50%	12.27	6.10%
South Korea	5.22	6.94	33.00%	7.98	15.00%
North America	5.27	7.15	35.70%	7.33	2.50%
China	3.38	4.98	47.30%	5.06	1.60%
Japan	3.38	3.65	8.00%	4.22	15.60%
Europe	1.92	2.49	29.70%	3.68	47.80%
ROW	2.08	1.66	-20.20%	2.05	23.50%
Total	31.82	38.44	20.80%	42.59	10.80%

Resource : July 2014 ; Semi

Products

Wafer Reclaim

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Advanced clean technology
20nm/ 16nm Particle
Low trace metal (<5E9)

Complete particle inspecti
(SP1-DLS & SP2)

Cleaning

Etching

Full Process Optimization

Polishing

Grinding

Complete polishing process
Single side polish
Double side polish
Final Haze polish

Super flatness
(GBIR<0.5μm)

- 12” Wafer Reclaim
- Capacity: 120K / month
- Separated Cu & Non Cu Line

Products

Wafer Reclaim

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Global market for Silicon Reclaim Wafers is projected to reach US$747.9 million by 2020

Major Players...

- *Advantec Co Ltd.*
- *KST World Corp.*
- *MOSPEC Semiconductor Corporation*
- *North East Silicon Technologies, Inc.*
- *Pure Wafer PLC*
- *Phoenix Silicon International Corporation (PSI)*
- *Rockwood Wafer Reclaim SAS.*
- *RS Technologies Co., LTD*
- *Silicon, Inc.*
- *Scientech Corporation*

Resource : February 2014 ; Global Industry Analysts

Wafer Reclaim

Major Silicon Players Technology Roadmap Comparison

	2010	2011	2012	2013	2014E	2015E	2016E	2017E	2018E
Intel	32nm HKMG		22nm TG		14nm		10nm		7nm
TSMC	40/45nm		28nm SiON/HKMG		20nm SOC/16nm FF		10nm		7nm
SEC	45nm	32/28nm			20nm	14nm FF		10nm	
UMC	40/45nm			28nm		20nm planar/FF		14nm FF	10nm
GF	45nm		32/28nm		22/20nm		14nm FF		10nm

Source: Daiwa forecasts

**HKMG = high K metal gate; TG = TriGate; SiON = Silicon Oxinitride; FF = FinFET, GF = Global Foundries*

Products

Equipment Distributor

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Multi application

Exclusive Agency

Supply Chain Partnership

ExOne
DIGITAL PART MATERIALIZATION
Canon
ReVera
RAVE
ECO-SNOW SYSTEMS
POONGSAN MICROTEC
FerroTec
xradia
insight in 3D
Hirata
ADVANCED ENERGY
Plasma-Therm
USHIO
UCP
PLASMA TECHNOLOGIES
KLA Tencor
Already there
e2
VLSI Standards Incorporated
RUDOLPH RESEARCH ANALYTICAL
FRT
タカノ株式会社
NAKAN
Ayumi
AYUMI INDUSTRY CO.,LTD.
アユミ工業株式会社
Kensington
LABORATORIES
Verity
INSTRUMENTS, INC.
OAI
NST [주]엔에스티
NST INC.

Future Prospect

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Equipment

1.Geometry migration

2. New business scope extended from core technology

- Laser technology
- Single Wafer Wet Process Equipment
- Full spectrum mass spectrometer

Wafer Reclaim

1. Geometry migration
2. Non-silicon material wafer technology

- 20/16/10 nm wafer reclaim technology
- Non-silicon material wafer technology
  - SiC (silicon carbide): high power component/ RF/VE/ HBLED
  - Ge (germanium) : HC PV
  - Glass: 3D IC wafer carrier

Future Prospect

Equipment

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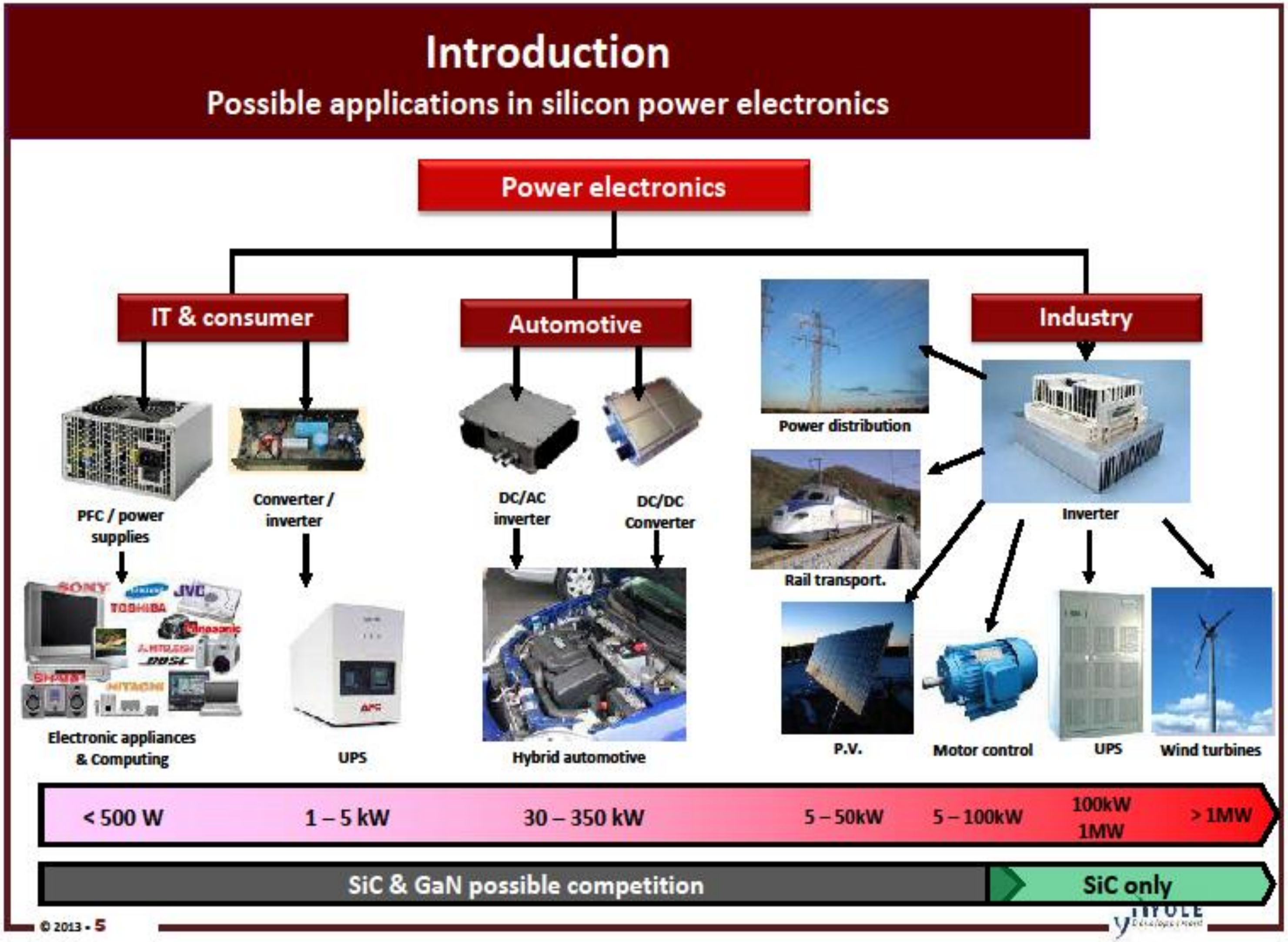
- **12 inch Wet Process Equipment**
  - **Advanced Wafer level packaging**

    (InFo 、 RDL 、Copper pillow 、 Bumping 、 TSV)
    - UBM etch
    - Wafer clean
    - PR develop
    - PR Strip
    - Flux clean
    - bump scrubbing
    - Electro-less plating

- **6”/8”/12” Mature Special Process for IoT & wearable devices**

  (FP sensor、RF、CMOS、Touch Controller、**Power IC**、MEMS 、 IoT sensors)

SiC: Application



Introduction

Possible applications in silicon power electronics

Power electronics

IT & consumer
- PFC / power supplies
  - Electronic appliances & Computing
- Converter / inverter
  - UPS

Automotive
- DC/AC inverter
- DC/DC Converter
  - Hybrid automotive

Industry
- Inverter
  - Power distribution
  - Rail transport.
  - P.V.
  - Motor control
  - UPS
  - Wind turbines

< 500 W | 1 – 5 kW | 30 – 350 kW | 5 – 50kW | 5 – 100kW | 100kW 1MW | > 1MW

SiC & GaN possible competition | SiC only

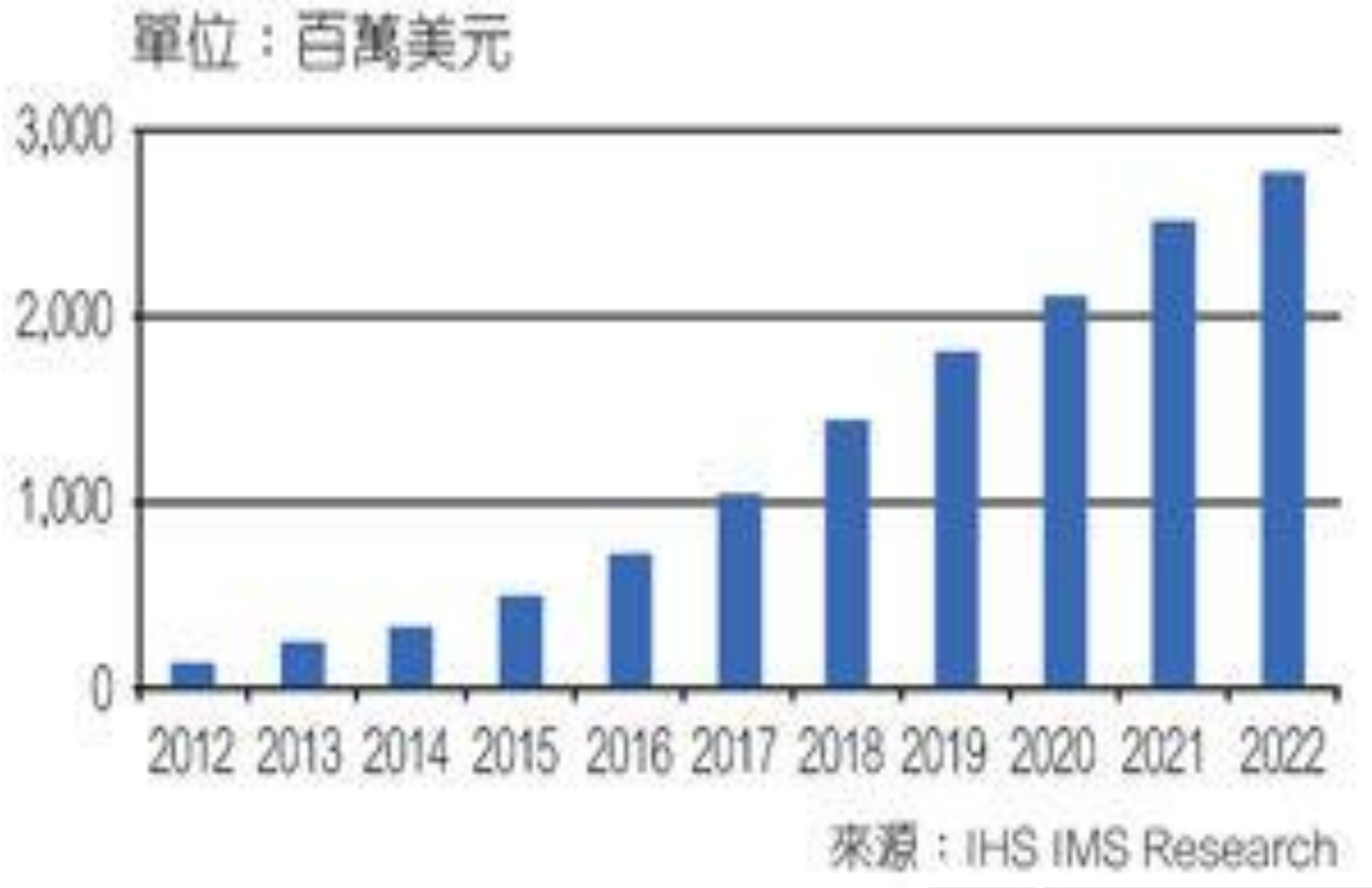
© 2013 - 5

YOLE Développement

Source: Yole Development

Future Prospect

SiC/GaN Power Semiconductor

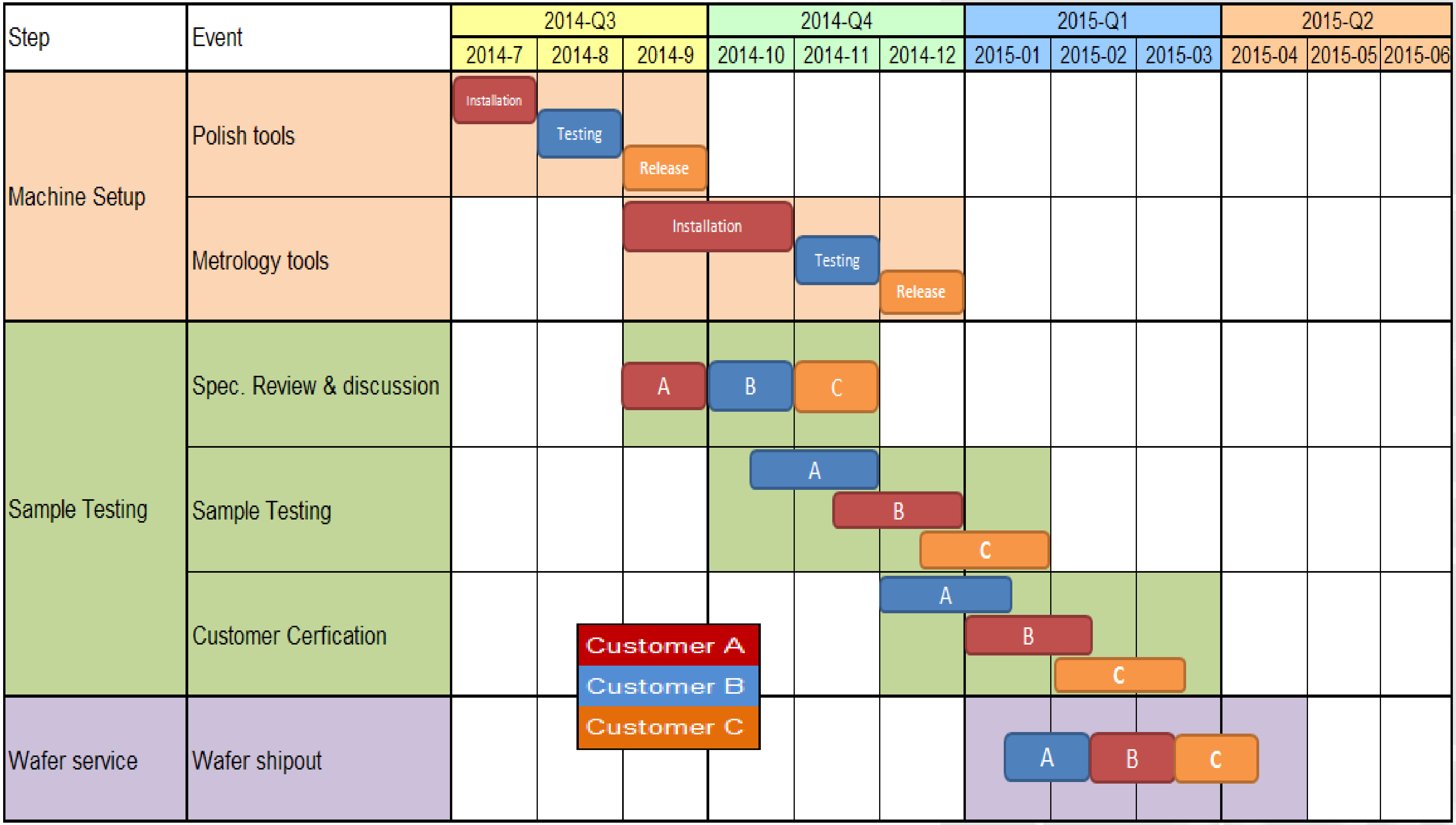


來源：IHS IMS Research

Future Prospect

SiC Wafer Reclaim Roadmap

SCIENTECH



Step	Event	2014-Q3			2014-Q4			2015-Q1			2015-Q2		
		2014-7	2014-8	2014-9	2014-10	2014-11	2014-12	2015-01	2015-02	2015-03	2015-04	2015-05	2015-06
Machine Setup	Polish tools	Installation	Testing	Release									
	Metrology tools			Installation		Testing	Release						
Sample Testing	Spec. Review & discussion			A	B	C							
	Sample Testing				A	B	C						
	Customer Cerfication						A	B	C				
Wafer service	Wafer shipout							A	B	C			

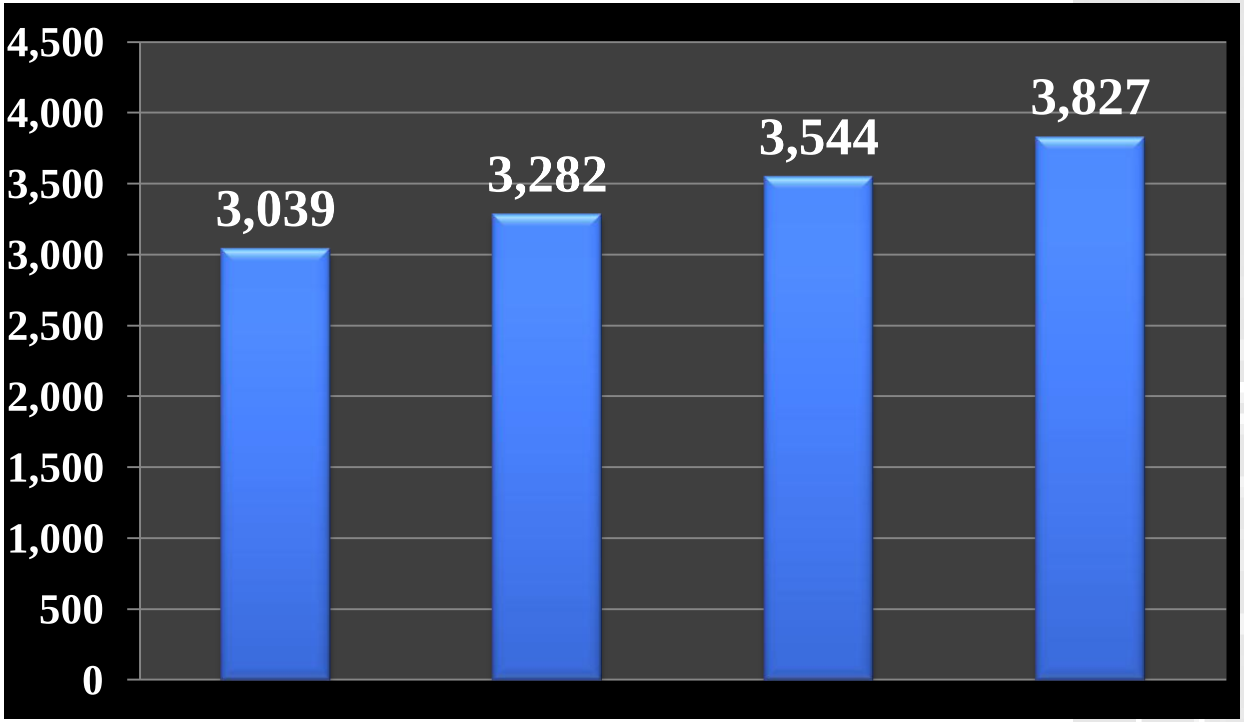
Customer A
Customer B
Customer C

Mass spectrometer

- **Mass spectrometry**
  - With patented frequency scan, it is capable to analyze mass range beyond conventional Mass Spectrometry .
  - Dual ion sources, MALDI and ESI, it can analyze both solid and liquid samples.
  - Applications to explore
    - Food inspection
    - Environmental monitoring
    - Bio macromolecule
    - Clinical medicine
    - Medicine and pharmacology

Future Prospect

Mass spectrometer



⇧ 8%

Currently MS market do not include macro-molecules (>1E5Da)

Instrument Business Outlook January 15, 2011
(US$ B)

Thank You